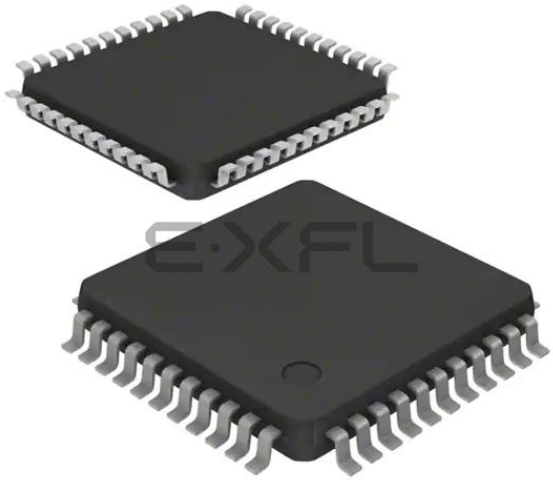

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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of Embedded - Microprocessors

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details	
Product Status	Active
Core Processor	Z80
Number of Cores/Bus Width	1 Core, 8-Bit
Speed	10MHz
Co-Processors/DSP	-
RAM Controllers	-
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	-
SATA	-
USB	-
Voltage - I/O	5.0V
Operating Temperature	-40°C ~ 100°C (TA)
Security Features	-
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z84c0010aeg

address. This flexibility in selecting the interrupt service routine address allows the peripheral device to use several different types of service routines. These routines may be located at any available location in memory. Since the interrupting device supplies the low-order byte of the 2-byte vector, bit 0 (A_0) must be a zero.

Interrupt Enable/Disable Operation. Two flip-flops, IFF_1 and IFF_2, referred to in the register description, are used to signal the CPU interrupt status. Operation of the two flip-flops is described in Table 2. For more details, refer to the *Z80 CPU Technical Manual* (03-0029-01) and *Z80 Assembly Language Programming Manual* (03-0002-01).

Table 2. State of Flip-Flops

Action	IFF_1	IFF_2	Comments
CPU Reset	0	0	Maskable interrupt $\overline{INT}$ disabled
DI instruction execution	0	0	Maskable interrupt $\overline{INT}$ disabled
EI instruction execution	1	1	Maskable interrupt $\overline{INT}$ enabled
LD A,I instruction execution	•	•	$IFF_2 \rightarrow$ Parity flag
LD A,R instruction execution	•	•	$IFF_2 \rightarrow$ Parity flag
Accept $\overline{NMI}$	0	•	Maskable interrupt $\overline{INT}$ disabled
RETN instruction execution	IFF_2	•	$IFF_2 \rightarrow IFF_1$ at completion of an $\overline{NMI}$ service routine.

INSTRUCTION SET

The microprocessor has one of the most powerful and versatile instruction sets available in any 8-bit microprocessor. It includes such unique operations as a block move for fast, efficient data transfers within memory, or between memory and I/O. It also allows operations on any bit in any location in memory.

The following is a summary of the instruction set which shows the assembly language mnemonic, the operation, the flag status, and gives comments on each instruction. For an explanation of flag notations and symbols for mnemonic tables, see the Symbolic Notations section which follows these tables. The *Z80 CPU Technical Manual* (03-0029-01), the *Programmer's Reference Guide* (03-0012-03), and *Assembly Language Programming Manual* (03-0002-01) contain significantly more details for programming use.

The instructions are divided into the following categories:

- 8-bit loads
- 16-bit loads
- Exchanges, block transfers, and searches
- 8-bit arithmetic and logic operations
- General-purpose arithmetic and CPU control
- 16-bit arithmetic operations
- Rotates and shifts
- Bit set, reset, and test operations
- Jumps
- Calls, returns, and restarts
- Input and output operations

A variety of addressing modes are implemented to permit efficient and fast data transfer between various registers, memory locations, and input/output devices. These addressing modes include:

- Immediate
- Immediate extended
- Modified page zero
- Relative
- Extended
- Indexed
- Register
- Register indirect
- Implied
- Bit

8-BIT LOAD GROUP

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
LD r, r'	r ← r'	•	•	X	•	X	•	•	•	01	r	r'		1	1	4	r, r' Reg.
LD r, n	r ← n	•	•	X	•	X	•	•	•	00	r	110		2	2	7	000 B
											← n →						001 C
LD r, (HL)	r ← (HL)	•	•	X	•	X	•	•	•	01	r	110		1	2	7	010 D
LD r, (IX + d)	r ← (IX + d)	•	•	X	•	X	•	•	•	11	011	101	DD	3	5	19	011 E
										01	r	110					100 H
											← d →						101 L
LD r, (IY + d)	r ← (IY + d)	•	•	X	•	X	•	•	•	11	111	101	FD	3	5	19	111 A
										01	r	110					
											← d →						
LD (HL), r	(HL) ← r	•	•	X	•	X	•	•	•	01	110	r		1	2	7	
LD (IX + d), r	(IX + d) ← r	•	•	X	•	X	•	•	•	11	011	101	DD	3	5	19	
										01	110	r					
											← d →						
LD (IY + d), r	(IY + d) ← r	•	•	X	•	X	•	•	•	11	111	101	FD	3	5	19	
										01	110	r					
											← d →						
LD (HL), n	(HL) ← n	•	•	X	•	X	•	•	•	00	110	110	36	2	3	10	
											← n →						
LD (IX + d), n	(IX + d) ← n	•	•	X	•	X	•	•	•	11	011	101	DD	4	5	19	
										00	110	110	36				
											← d →						
											← n →						

8-BIT LOAD GROUP (Continued)

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
LD (IY+d), n	(IY+d) ← n	•	•	X	X	•	•	•	11	111	101	FD	4	5	19	
									00	110	110	36				
									← d →							
									← n →							
LD A, (BC)	A ← (BC)	•	•	X	X	•	•	•	00	001	010	0A	1	2	7	
LD A, (DE)	A ← (DE)	•	•	X	X	•	•	•	00	011	010	1A	1	2	7	
LD A, (nn)	A ← (nn)	•	•	X	X	•	•	•	00	111	010	3A	3	4	13	
									← n →							
									← n →							
LD (BC), A	(BC) ← A	•	•	X	X	•	•	•	00	000	010	02	1	2	7	
LD (DE), A	(DE) ← A	•	•	X	X	•	•	•	00	010	010	12	1	2	7	
LD (nn), A	(nn) ← A	•	•	X	X	•	•	•	00	110	010	32	3	4	13	
									← n →							
									← n →							
LD A, I	A ← I	‡	‡	X	X	IFF	0	•	11	101	101	ED	2	2	9	
									01	010	111	57				
LD A, R	A ← R	‡	‡	X	X	IFF	0	•	11	101	101	ED	2	2	9	
									01	011	111	5F				
LD I, A	I ← A	•	•	X	X	•	•	•	11	101	101	ED	2	2	9	
									01	000	111	47				
LD R, A	R ← A	•	•	X	X	•	•	•	11	101	101	ED	2	2	9	
									01	001	111	4F				

NOTE: IFF, the content of the interrupt enable flip-flop, (IFF_2), is copied into the P/V flag.

16-BIT LOAD GROUP

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments	
LD dd, nn	dd ← nn	•	•	X	X	•	•	•	00	dd0	001		3	3	10	dd Pair
									← n →							00 BC
									← n →							01 DE
LD IX, nn	IX ← nn	•	•	X	X	•	•	•	11	011	101	DD	4	4	14	10 HL
									00	100	001	21				11 SP
									← n →							
									← n →							
LD IY, nn	IY ← nn	•	•	X	X	•	•	•	11	111	101	FD	4	4	14	
									00	100	001	21				
									← n →							
									← n →							
LD HL, (nn)	H ← (nn+1)	•	•	X	X	•	•	•	00	101	010	2A	3	5	16	
	L ← (nn)															
									← n →							
									← n →							
LD dd, (nn)	dd_H ← (nn+1)	•	•	X	X	•	•	•	11	101	101	ED	4	6	20	
	dd_L ← (nn)								01	dd1	011					
									← n →							
									← n →							

NOTE: $(PAIR)_H$, $(PAIR)_L$ refer to high order and low order eight bits of the register pair respectively. e.g., BC_L = C, AF_H = A.

EXCHANGE, BLOCK TRANSFER, BLOCK SEARCH GROUPS

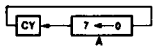
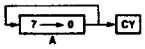
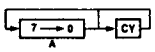
Mnemonic	Symbolic Operation	Flags S	Z		H		P/V	N	C	Opcode 76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
EX DE, HL	DE ↔ HL	•	•	X	•	X	•	•	•	11	101	011	EB	1	1	4	
EX AF, AF′	AF ↔ AF′	•	•	X	•	X	•	•	•	00	001	000	08	1	1	4	
EXX	BC ↔ BC′ DE ↔ DE′ HL ↔ HL′	•	•	X	•	X	•	•	•	11	011	001	D9	1	1	4	Register bank and auxiliary register bank exchange
EX (SP), HL	H ↔ (SP + 1) L ↔ (SP)	•	•	X	•	X	•	•	•	11	100	011	E3	1	5	19	
EX (SP), IX	IX_H ↔ (SP + 1) IX_L ↔ (SP)	•	•	X	•	X	•	•	•	11 11	011 100	101 011	DD E3	2	6	23	
EX (SP), IY	IY_H ↔ (SP + 1) IYL ↔ (SP)	•	•	X	•	X	•	•	•	11 11	111 100	101 011	FD E3	2	6	23	
LDI	(DE) ← (HL) DE ← DE + 1 HL ← HL + 1 BC ← BC − 1	•	•	X	0	X	↕ ①	0	•	11 10	101 100	101 000	ED A0	2	4	16	Load (HL) into (DE), increment the pointers and decrement the byte counter (BC)
LDIR	(DE) ← (HL) DE ← DE + 1 HL ← HL + 1 BC ← BC − 1 Repeat until BC = 0	•	•	X	0	X	0 ②	0	•	11 10	101 110	101 000	ED B0	2 2	5 4	21 16	If BC ≠ 0 If BC = 0
LDD	(DE) ← (HL) DE ← DE − 1 HL ← HL − 1 BC ← BC − 1	•	•	X	0	X	↕ ①	0	•	11 10	101 101	101 000	ED A8	2	4	16	
LDDR	(DE) ← (HL) DE ← DE − 1 HL ← HL − 1 BC ← BC − 1 Repeat until BC = 0	•	•	X	0	X	0 ②	0	•	11 10	101 111	101 000	ED B8	2 2	5 4	21 16	If BC ≠ 0 If BC = 0
CPI	A − (HL) HL ← HL + 1 BC ← BC − 1	↕	↕ ③	X	↕	X	↕ ①	1	•	11 10	101 100	101 001	ED A1	2	4	16	

NOTE: ① P/V flag is 0 if the result of BC − 1 = 0, otherwise P/V = 1.
② P/V flag is 0 only at completion of instruction.
③ Z flag is 1 if A = HL, otherwise Z = 0.

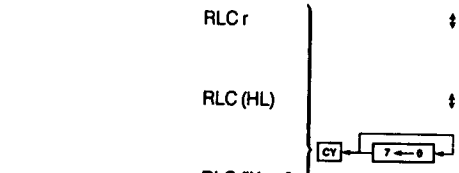
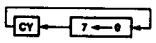
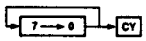
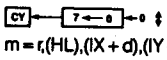
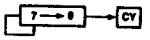
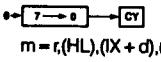
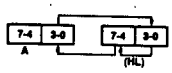
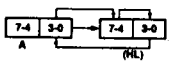
16-BIT ARITHMETIC GROUP

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
ADD HL, ss	HL ← HL + ss	•	•	X	X	X	•	0	‡	00	ssl	001		1	3	11	ss Reg. 00 BC
ADC HL, ss	HL ←																01 DE
	HL + ss + CY	‡	‡	X	X	X	V	0	‡	11	101	101	ED	2	4	15	10 HL
										01	ss1	010					11 SP
SBC HL, ss	HL ←																
	HL − ss − CY	‡	‡	X	X	X	V	1	‡	11	101	101	ED	2	4	15	
										01	ss0	010					
ADD IX, pp	IX ← IX + pp	•	•	X	X	X	•	0	‡	11	011	101	DD	2	4	15	pp Reg. 00 BC
										01	pp1	001					01 DE 10 IX 11 SP
ADD IY, rr	IY ← IY + rr	•	•	X	X	X	•	0	‡	11	111	101	FD	2	4	15	rr Reg. 00 BC
										00	rr1	001					01 DE
INC ss	ss ← ss + 1	•	•	X	•	X	•	•	•	00	ss0	011		1	1	6	10 IY
INC IX	IX ← IX + 1	•	•	X	•	X	•	•	•	11	011	101	DD	2	2	10	11 SP
										00	100	011	23				
INC IY	IY ← IY + 1	•	•	X	•	X	•	•	•	11	111	101	FD	2	2	10	
										00	100	011	23				
DEC ss	ss ← ss − 1	•	•	X	•	X	•	•	•	00	ss1	011		1	1	6	
DEC IX	IX ← IX − 1	•	•	X	•	X	•	•	•	11	011	101	DD	2	2	10	
										00	101	011	2B				
DEC IY	IY ← IY − 1	•	•	X	•	X	•	•	•	11	111	101	FD	2	2	10	
										00	101	011	2B				

ROTATE AND SHIFT GROUP

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
RLCA		•	•	X	0	X	•	0	‡	00	000	111	07	1	1	4	Rotate left circular accumulator.
RLA		•	•	X	0	X	•	0	‡	00	010	111	17	1	1	4	Rotate left accumulator.
RRCA		•	•	X	0	X	•	0	‡	00	001	111	0F	1	1	4	Rotate right circular accumulator.
RRA		•	•	X	0	X	•	0	‡	00	011	111	1F	1	1	4	Rotate right accumulator.

ROTATE AND SHIFT GROUP (Continued)

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	Opcode 76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
RLC r		↕	↕	X	P/V	X	↕	11	001	011	CB	2	2	8	Rotate left circular register r.
								00	000	r					r Reg. 000 B 001 C 010 D 011 E 001 H 101 L 111 A
RLC (HL)		↕	↕	X	P/V	X	↕	11	001	011	CB	2	4	15	
								00	000	110					
RLC (IX+d)		↕	↕	X	P/V	X	↕	11	011	101	DD	4	6	23	
	r,(HL),(IX+d),(IY+d)							11	001	011	CB				
									←d→						
								00	000	110					
RLC (IY+d)		↕	↕	X	P/V	X	↕	11	111	101	FD	4	6	23	
								11	001	011	CB				
									←d→						
								00	000	110					Instruction format and states are as shown for RLCs. To form new opcode replace 000 of RLCs with shown code.
RL m		↕	↕	X	P/V	X	↕		010						
	m = r,(HL),(IX+d),(IY+d)														
RRC m		↕	↕	X	P/V	X	↕		001						
	m = r,(HL),(IX+d),(IY+d)														
RR m		↕	↕	X	P/V	X	↕		011						
	m = r,(HL),(IX+d),(IY+d)														
SLA m		↕	↕	X	P/V	X	↕		100						
	m = r,(HL),(IX+d),(IY+d)														
SRA m		↕	↕	X	P/V	X	↕		101						
	m = r,(HL),(IX+d),(IY+d)														
SRL m		↕	↕	X	P/V	X	↕		111						
	m = r,(HL),(IX+d),(IY+d)														
RLD		↕	↕	X	P/V	X	•	11	101	101	ED	2	5	18	Rotate digit left and right between the accumulator and location (HL). The content of the upper half of the accumulator is unaffected.
								01	101	111	6F				
RRD		↕	↕	X	P/V	X	•	11	101	101	ED	2	5	18	
								01	100	111	67				

BIT SET, RESET AND TEST GROUP

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
BIT b, r	$Z \leftarrow r_b$	X	‡	X	X	0	•	11	001	011	CB	2	2	8	r Reg.
								01	b	r					000 B
BIT b, (HL)	$Z \leftarrow (HL)_b$	X	‡	X	X	0	•	11	001	011	CB	2	3	12	001 C
								01	b	110					010 D
BIT b,(IX+d)	$Z \leftarrow (IX+d)_b$	X	‡	X	X	0	•	11	011	101	DD	4	5	20	011 E
								11	001	011	CB				100 H
									←d→						101 L
								01	b	110					111 A
BIT b, (IY+d)	$Z \leftarrow (IY+d)_b$	X	‡	X	X	0	•	11	111	101	FD	4	5	20	b Bit Tested
								11	001	011	CB				000 0
									←d→						001 1
								01	b	110					010 2
SET b, r	$r_b \leftarrow 1$	•	•	X	X	•	•	11	001	011	CB	2	2	8	011 3
								[11]	b	r					100 4
SET b, (HL)	$(HL)_b \leftarrow 1$	•	•	X	X	•	•	11	001	011	CB	2	4	15	101 5
								[11]	b	110					110 6
SET b, (IX+d)	$(IX+d)_b \leftarrow 1$	•	•	X	X	•	•	11	011	101	DD	4	6	23	111 7
								11	001	011	CB				
									←d→						
								[11]	b	110					
SET b, (IY+d)	$(IY+d)_b \leftarrow 1$	•	•	X	X	•	•	11	111	101	FD	4	6	23	
								11	001	011	CB				
									←d→						
								[11]	b	110					
RES b, m	$m_b \leftarrow 0$ m≡r, (HL), (IX+d), (IY+d)	•	•	X	X	•	•	[10]							To form new opcode replace [11] of SET b, s with [10]. Flags and time states for SET instruction.

NOTE: The notation m_b indicates location m, bit b (0 to 7).

JUMP GROUP

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
JP nn	PC ← nn	•	•	X	•	X	•	•	•	11	000	011	C3	3	3	10	cc Condition
											← n →						000 NZ (non-zero)
											← n →						001 Z (zero)
JP cc, nn	If condition cc	•	•	X	•	X	•	•	•	11	cc	010		3	3	10	010 NC (non-carry)
	is true PC ← nn,										← n →						011 C (carry)
	otherwise										← n →						100 PO (parity odd)
	continue																101 PE (parity even)
JR e	PC ← PC + e	•	•	X	•	X	•	•	•	00	011	000	18	2	3	12	110 P (sign positive)
											← e − 2 →						111 M (sign negative)
JR C, e	If C = 0,	•	•	X	•	X	•	•	•	00	111	000	38	2	2	7	If condition not met.
	continue										← e − 2 →						
	If C = 1,													2	3	12	If condition is met.
	PC ← PC + e																
JR NC, e	IF C = 1,	•	•	X	•	X	•	•	•	00	110	000	30	2	2	7	If condition not met.
	continue										← e − 2 →						
	If C = 0,													2	3	12	If condition is met.
	PC ← PC + e																
JP Z, e	If Z = 0	•	•	X	•	X	•	•	•	00	101	000	28	2	2	7	If condition not met.
	continue										← e − 2 →						
	If Z = 1,													2	3	12	If condition is met.
	PC ← PC + e																
JR NZ, e	If Z = 1,	•	•	X	•	X	•	•	•	00	100	000	20	2	2	7	If condition not met.
	continue										← e − 2 →						
	If Z = 0,													2	3	12	If condition is met.
	PC ← PC + e																
JP (HL)	PC ← HL	•	•	X	•	X	•	•	•	11	101	001	E9	1	1	4	
JP (IX)	PC ← IX	•	•	X	•	X	•	•	•	11	011	101	DD	2	2	8	
										11	101	001	E9				
JP (IY)	PC ← IY	•	•	X	•	X	•	•	•	11	111	101	FD	2	2	8	
										11	101	001	E9				
DJNZ, e	B ← B − 1	•	•	X	•	X	•	•	•	00	010	000	10	2	2	8	If B = 0
	If B = 0,										← e − 2 →						
	continue																
	If B≠0,													2	3	13	If B≠0.
	PC ← PC + e																

NOTES: e represents the extension in the relative addressing mode.
e is a signal two's complement number in the range < − 126, 129 >.
e − 2 in the opcode provides an effective address of pc + e as PC is incremented by 2 prior to the addition of e.

CALL AND RETURN GROUP

Mnemonic	Symbolic Operation	S	Z	H	P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
CALL nn	$(SP-1)\leftarrow PC_H$ $(SP-2)\leftarrow PC_L$ $PC\leftarrow nn$,	•	•	X	•	X	•	11	001 ←n→ ←n→	101	CD	3	5	17	
CALL cc,nn	If condition cc is false	•	•	X	•	X	•	11	cc ←n→	100		3	3	10	If cc is false.
	continue, otherwise same as CALL nn								←n→			3	5	17	If cc is true.
RET	$PC_L\leftarrow(SP)$ $PC_H\leftarrow(SP+1)$	•	•	X	•	X	•	11	001	001	C9	1	3	10	
RET cc	If condition cc is false	•	•	X	•	X	•	11	cc	000		1	1	5	If cc is false.
	continue, otherwise same as RET											/1	3	11	If cc is true.
RETI	Return from interrupt	•	•	X	•	X	•	11 01	101 001	101 101	ED 4D	2	4	14	
RETN[1]	Return from non-maskable interrupt	•	•	X	•	X	•	11 01	101 000	101 101	ED 45	2	4	14	
RST p	$(SP-1)\leftarrow PC_H$ $(SP-2)\leftarrow PC_L$ $PC_H\leftarrow 0$ $PC_L\leftarrow p$	•	•	X	•	X	•	11	t	111		1	3	11	

cc	Condition
000	NZ (non-zero)
001	Z (zero)
010	NC (non-carry)
011	C (carry)
100	PO (parity odd)
101	PE (parity even)
110	P (sign positive)
111	M (sign negative)

t	p
000	00H
001	08H
010	10H
011	18H
100	20H
101	28H
110	30H
111	38H

NOTE: [1]RETN loads $IFF_2\rightarrow IFF_1$

INPUT AND OUTPUT GROUP

Mnemonic	Symbolic Operation	S	Z		H		P/V	N	C	76	543	210	Hex	No. of Bytes	No. of M Cycles	No. of T States	Comments
IN A, (n)	A ← (n)	•	•	X	•	X	•	•	•	11	011	01	DB	2	3	11	n to $A_0 \sim A_7$
											← n →						Acc. to $A_8 \sim A_{15}$
IN r, (C)	r ← (C)	‡	‡	X	‡	X	P	0	•	11	101	101	ED	2	3	12	C to $A_0 \sim A_7$
	if r = 110 only									01	r	000					B to $A_8 \sim A_{15}$
	the flags will																
	be affected																
			①														
INI	(HL) ← (C)	X	‡	X	X	X	X	1	X	11	101	101	ED	2	4	16	C to $A_0 \sim A_7$
	B ← B − 1									10	100	010	A2				B to $A_8 \sim A_{15}$
	HL ← HL + 1		②														
INIR	(HL) ← (C)	X	1	X	X	X	X	1	X	11	101	101	ED	2	5	21	C to $A_0 \sim A_7$
	B ← B − 1									10	110	010	B2		(If B≠0)		B to $A_8 \sim A_{15}$
	HL ← HL + 1													2	4	16	
	Repeat until														(If B = 0)		
	B = 0																
			①														
IND	(HL) ← (C)	X	‡	X	X	X	X	1	X	11	101	101	ED	2	4	16	C to $A_0 \sim A_7$
	B ← B − 1									10	101	010	AA				B to $A_8 \sim A_{15}$
	HL ← HL − 1		②														
INDR	(HL) ← (C)	X	1	X	X	X	X	1	X	11	101	101	ED	2	5	21	C to $A_0 \sim A_7$
	B ← B − 1									10	111	010	BA		(If B≠0)		B to $A_8 \sim A_{15}$
	HL ← HL − 1													2	4	16	
	Repeat until														(If B = 0)		
	B = 0																
OUT (n), A	(n) ← A	•	•	X	•	X	•	•	•	11	010	011	D3	2	3	11	n to $A_0 \sim A_7$
											← n →						Acc. to $A_8 \sim A_{15}$
OUT (C), r	(C) ← r	•	•	X	•	X	•	•	•	11	101	101	ED	2	3	12	C to $A_0 \sim A_7$
										01	r	001					B to $A_8 \sim A_{15}$
			①														
OUTI	(C) ← (HL)	X	‡	X	X	X	X	1	X	11	101	101	ED	2	4	16	C to $A_0 \sim A_7$
	B ← B − 1									10	100	011	A3				B to $A_8 \sim A_{15}$
	HL ← HL + 1		②														
OTIR	(C) ← (HL)	X	1	X	X	X	X	1	X	11	101	101	ED	2	5	21	C to $A_0 \sim A_7$
	B ← B − 1									10	110	011	B3		(If B≠0)		B to $A_8 \sim A_{15}$
	HL ← HL + 1													2	4	16	
	Repeat until														(If B = 0)		
	B = 0																
			①														
OUTD	(C) ← (HL)	X	‡	X	X	X	X	1	X	11	101	101	ED	2	4	16	C to $A_0 \sim A_7$
	B ← B − 1									10	101	011	AB				B to $A_8 \sim A_{15}$
	HL ← HL − 1																
			②														
OTDR	(C) ← (HL)	X	1	X	X	X	X	1	X	11	101	101	ED	2	5	21	C to $A_0 \sim A_7$
	B ← B − 1									10	111	011			(If B≠0)		B to $A_8 \sim A_{15}$
	HL ← HL − 1													2	4	16	
	Repeat until														(If B = 0)		
	B = 0																

NOTES: ① If the result of B − 1 is zero, the Z flag is set; otherwise it is reset.
② Z flag is set upon instruction completion only.

PIN DESCRIPTIONS

A_0-A_{15}. *Address Bus* (output, active High, 3-state). A_0-A_{15} form a 16-bit address bus. The Address Bus provides the address for memory data bus exchanges (up to 64K bytes) and for I/O device exchanges.

$\overline{\text{BUSACK}}$. *Bus Acknowledge* (output, active Low). Bus Acknowledge indicates to the requesting device that the CPU address bus, data bus, and control signals $\overline{\text{MREQ}}$, $\overline{\text{IORQ}}$, $\overline{\text{RD}}$, and $\overline{\text{WR}}$ have entered their high-impedance states. The external circuitry can now control these lines.

$\overline{\text{BUSREQ}}$. *Bus Request* (input, active Low). Bus Request has a higher priority than $\overline{\text{NMI}}$ and is always recognized at the end of the current machine cycle. $\overline{\text{BUSREQ}}$ forces the CPU address bus, data bus, and control signals $\overline{\text{MREQ}}$, $\overline{\text{IORQ}}$, RD, and WR to go to a high-impedance state so that other devices can control these lines. $\overline{\text{BUSREQ}}$ is normally wired-OR and requires an external pullup for these applications. Extended $\overline{\text{BUSREQ}}$ periods due to extensive DMA operations can prevent the CPU from properly refreshing dynamic RAMs.

D_0-D_7. *Data Bus* (input/output, active High, 3-state). D_0-D_7 constitute an 8-bit bidirectional data bus, used for data exchanges with memory and I/O.

$\overline{\text{HALT}}$. *Halt State* (output, active Low). $\overline{\text{HALT}}$ indicates that the CPU has executed a Halt instruction and is awaiting either a nonmaskable or a maskable interrupt (with the mask enabled) before operation can resume. While halted, the CPU executes NOPs to maintain memory refresh.

$\overline{\text{INT}}$. *Interrupt Request* (input, active Low). Interrupt Request is generated by I/O devices. The CPU honors a request at the end of the current instruction if the internal software-controlled interrupt enable flip-flop (IFF) is enabled. $\overline{\text{INT}}$ is normally wired-OR and requires an external pullup for these applications.

$\overline{\text{IORQ}}$. *Input/Output Request* (output, active Low, 3-state). $\overline{\text{IORQ}}$ indicates that the lower half of the address bus holds a valid I/O address for an I/O read or write operation. $\overline{\text{IORQ}}$ is also generated concurrently with $\overline{\text{M1}}$ during an interrupt acknowledge cycle to indicate that an interrupt response vector can be placed on the data bus.

$\overline{\text{M1}}$. *Machine Cycle One* (output, active Low). $\overline{\text{M1}}$, together with $\overline{\text{MREQ}}$, indicates that the current machine cycle is the opcode fetch cycle of an instruction execution. $\overline{\text{M1}}$, together with $\overline{\text{IORQ}}$, indicates an interrupt acknowledge cycle.

$\overline{\text{MREQ}}$. *Memory Request* (output, active Low, 3-state). $\overline{\text{MREQ}}$ indicates that the address bus holds a valid address for a memory read or memory write operation.

$\overline{\text{NMI}}$. *Non-Maskable Interrupt* (input, negative edge-triggered). $\overline{\text{NMI}}$ has a higher priority than $\overline{\text{INT}}$. $\overline{\text{NMI}}$ is always recognized at the end of the current instruction, independent of the status of the interrupt enable flip-flop, and automatically forces the CPU to restart at location 0066H.

$\overline{\text{RD}}$. *Read* (output, active Low, 3-state). $\overline{\text{RD}}$ indicates that the CPU wants to read data from memory or an I/O device. The addressed I/O device or memory should use this signal to gate data onto the CPU data bus.

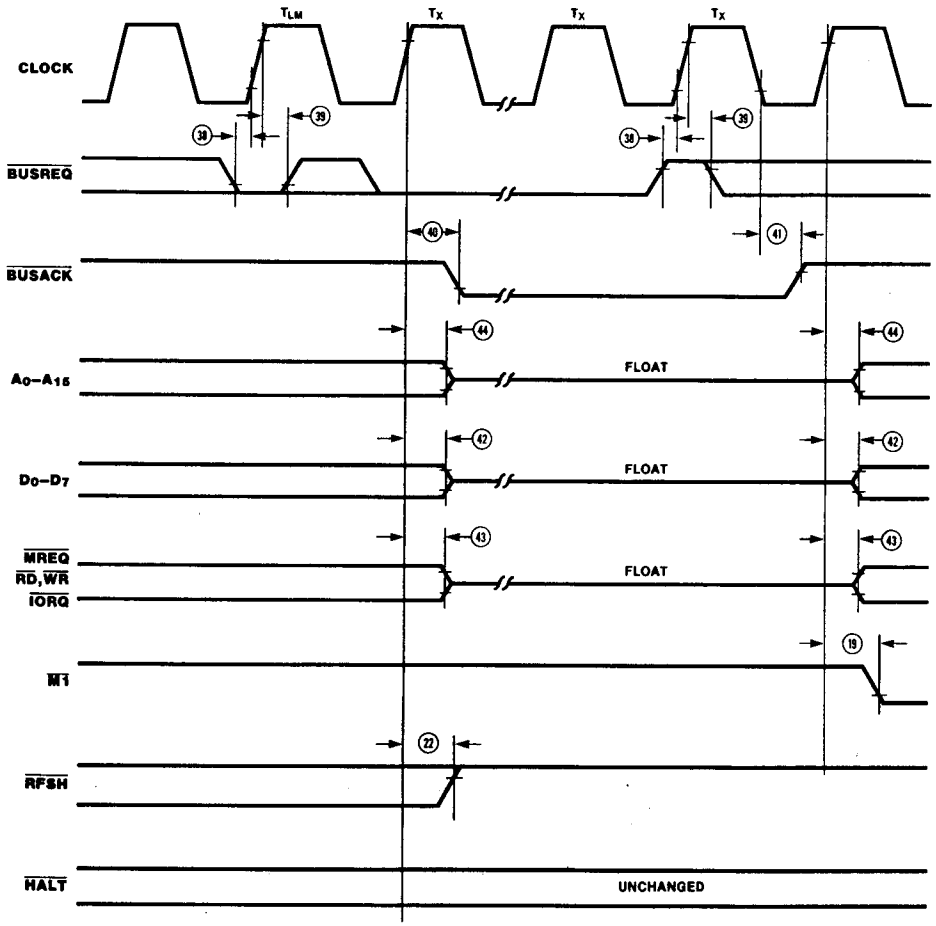
$\overline{\text{RESET}}$. *Reset* (input, active Low). $\overline{\text{RESET}}$ initializes the CPU as follows: it resets the interrupt enable flip-flop, clears the PC and Registers I and R, and sets the interrupt status to Mode 0. During reset time, the address and data bus go to a high-impedance state, and all control output signals go to the inactive state. Note that $\overline{\text{RESET}}$ must be active for a minimum of three full clock cycles before the reset operation is complete.

$\overline{\text{RFSH}}$. *Refresh* (output, active Low). $\overline{\text{RFSH}}$, together with $\overline{\text{MREQ}}$, indicates that the lower seven bits of the system's address bus can be used as a refresh address to the system's dynamic memories.

$\overline{\text{WAIT}}$. *Wait* (input, active Low). $\overline{\text{WAIT}}$ indicates to the CPU that the addressed memory or I/O devices are not ready for a data transfer. The CPU continues to enter a Wait state as long as this signal is active. Extended $\overline{\text{WAIT}}$ periods can prevent the CPU from properly refreshing dynamic memory.

$\overline{\text{WR}}$. *Write* (output, active Low, 3-state). $\overline{\text{WR}}$ indicates that the CPU data bus holds valid data to be stored at the addressed memory or I/O location.

Bus Request/Acknowledge Cycle. The CPU samples $\overline{BUSREQ}$ with the rising edge of the last clock period of any machine cycle (Figure 10). If $\overline{BUSREQ}$ is active, the CPU sets its address, data, and $\overline{MREQ}$, $\overline{IORQ}$, $\overline{RD}$, and $\overline{WR}$ lines to a high-impedance state with the rising edge of the next clock pulse. At that time, any external device can take control of these lines, usually to transfer data between memory and I/O devices.



NOTES: 1) T_{LM} = Last state of any M cycle.
2) T_X = An arbitrary clock cycle used by requesting device.

Figure 10. BUS Request/Acknowledge Cycle

Power-Down Release Cycle. The system clock must be supplied to the CPU to release the power-down state. When the system clock is supplied to the CLK input, the CPU restarts operations from the point at which the power-down state was implemented.

The timing diagrams for the release from power-down mode are shown in Figure 14.

NOTES:

1) When the external oscillator has been stopped to enter the power-down state, some warm-up time may be required to obtain a stable clock for the release.
2) When the HALT instruction is executed to enter the power-down state, the CPU will also enter the Halt state. An interrupt signal (either $\overline{NMI}$ or $\overline{INT}$) or a $\overline{RESET}$ signal must be applied to the CPU after the system clock is supplied in order to release the power-down state.

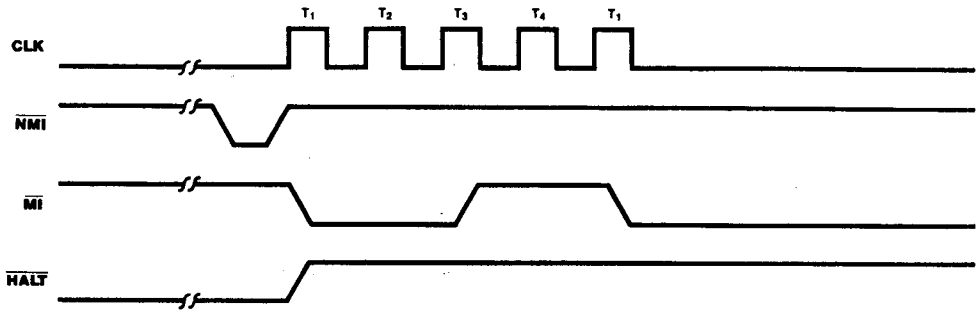


Figure 14a.

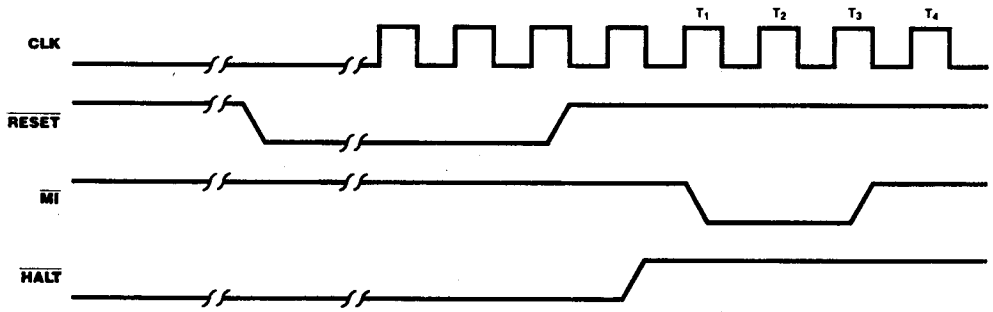


Figure 14b.

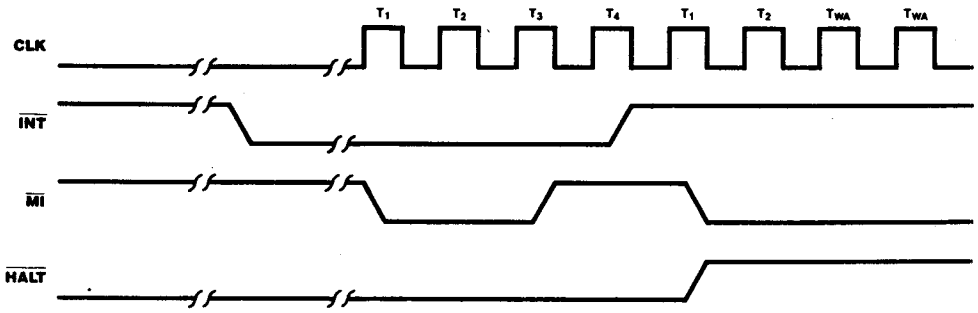


Figure 14c.

Figure 13. Power-Down Release

ABSOLUTE MAXIMUM RATINGS

Voltage on V_{CC} with respect to V_{SS} . . . . . −0.3V to +7V
Voltages on all inputs with respect to V_{SS} . . . . . −0.3V to V_{CC} + 0.3V
Operating Ambient Temperature . . . . . See Ordering Information
Storage Temperature . . . . . −65°C to +150°C

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

STANDARD TEST CONDITIONS

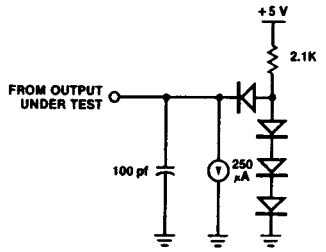
The DC Characteristics and capacitance sections below apply for the following standard test conditions, unless otherwise noted. All voltages are referenced to GND (0V). Positive current flows into the referenced pin.

Available operating temperature ranges are:

- **S = 0°C to +70°C**
  Voltage Supply Range:
  NMOS: +4.75V ≤ VCC ≤ +5.25V
  CMOS: +4.50V ≤ VCC ≤ +5.50V
- E= -40°C to 100°C, +4.50V ≤ VCC ≤ +5.50V

All ac parameters assume a load capacitance of 100 pf. Add 10 ns delay for each 50 pf increase in load up to a maximum of 200 pf for the data bus and 100 pf for address and control lines. AC timing measurements are referenced to 1.5 volts (except for clock, which is referenced to the 10% and 90% points).

The Ordering Information section lists temperature ranges and product numbers. Package drawings are in the Package Information section. Refer to the Literature List for additional documentation.



DC CHARACTERISTICS (Z84C00/CMOS Z80 CPU)

Symbol	Parameter	Min	Max	Unit	Condition
V_{ILC}	Clock Input Low Voltage	−0.3	0.45	V	
V_{IHC}	Clock Input High Voltage	V_{CC} − .6	V_{CC} + .3	V	
V_{IL}	Input Low Voltage	−0.3	0.8	V	
V_{IH}	Input High Voltage	2.2	V_{CC}	V	
V_{OL}	Output Low Voltage		0.4	V	I_{OL} = 2.0 mA
V_{OH_1}	Output High Voltage	2.4		V	I_{OH} = −1.6 mA
V_{OH_2}	Output High Voltage	V_{CC} − 0.8		V	I_{OH} = −250 μA
I_{CC_1}	Power Supply Current **4 MHz**		**20**	**mA**	V_{CC} = 5V
	6 MHz		**30**	**mA**	V_{IH} = V_{CC} − 0.2V
	8 MHz		**40**	**mA**	V_{IL} = 0.2V
	10 MHz		**50**	**mA**	
	20 MHz		100	mA	V_{cc} = 5V
I_{CC_2}	Standby Supply Current		10	μA	V_{CC} = 5V
					CLK = (0)
					V_{IH} = V_{CC} − 0.2V
					V_{IL} = 0.2V
I_{LI}	Input Leakage Current	−10	10	μA	V_{IN} = 0.4 to V_{CC}
I_{LO}	3-State Output Leakage Current in Float	−10	10^2	μA	V_{OUT} = 0.4 to V_{CC}

1. Measurements made with outputs floating.
2. A_{15}-A_0, D_7-D_0, $\overline{MREQ}$, $\overline{IORQ}$, $\overline{RD}$, and $\overline{WR}$.
3. I_{CC_2} standby supply current is guaranteed only when the supplied clock is stopped at a low level during T_4 of the machine cycle immediately following the execution of a HALT instruction.

CAPACITANCE

Symbol	Parameter	Min	Max	Unit
C_{CLOCK}	Clock Capacitance		**10**	pf
C_{IN}	Input Capacitance		5	pf
C_{OUT}	Output Capacitance		15	pf

T_A = 25°C, f = 1 MHz.
Unmeasured pins returned to ground.

AC CHARACTERISTICS† (Z84C00/CMOS Z80 CPU)

V_{cc}=5.0V ± 10%, unless otherwise specified

No	Symbol	Parameter	Z84C0004** Min	Z84C0004** Max	Z84C0006 Min	Z84C0006 Max	Z84C0008 Min	Z84C0008 Max	Z84C0010 Min	Z84C0010 Max	Z84C0020[1] Min	Z84C0020[1] Max	Unit	Note
1	TcC	Clock Cycle time	250*	DC	162*	DC	125*	DC	100*	DC	50*	DC	nS	
2	TwCh	Clock Pulse width (high)	110	DC	65	DC	55	DC	40	DC	20	DC	nS	
3	TwCl	Clock Pulse width (low)	110	DC	65	DC	55	DC	40	DC	20	DC	nS	
4	TfC	Clock Fall time		30		20		10		10		10	nS	
5	TrC	Clock Rise time		30		20		10		10		10	nS	
6	TdCr(A)	Address vaild from Clock Rise		110		90		80		65		57	nS	[2]
7	TdA(MREQf)	Address valid to /MREQ Fall	65*		35*		20*		5*		-15*		nS	
8	TdCf(MREQf)	Clock Fall to /MREQ Fall delay		85		70		60		55		40	nS	
9	TdCr(MREQr)	Clock Rise to /MREQ Rise delay		85		70		60		55		40	nS	
10	TwMREQh	/MREQ pulse width (High)	110*		65*		45**		30*		10*		nS	[3]
11	TwMREQl	/MREQ pulse width (low)	220*		132*		100*		75*		25*		nS	[3]
12	TdCf(MERQr)	Clock Fall to /MREQ Rise delay		85		70		60		55		40	nS	
13	TdCf(RDf)	Clock Fall to /RD Fall delay		95		80		70		65		40	nS	
14	TdCr(RDr)	Clock Rise to /RD Rise delay		85		70		60		55		40	nS	
15	TsD(Cr)	Data setup time to Clock Rise	35		30		30		25		12		nS	
16	ThD(RDr)	Data hold time after /RD Rise	0		0		0		0		0		nS	
17	TsWAIT(Cf)	/WAIT setup time to Clock Fall	70		60		50		20		7.5		nS	
18	ThWAIT(Cf)	/WAIT hold time after Clock Fall	10		10		10		10		10		nS	
19	TdCr(M1f)	Clock Rise to /M1 Fall delay		100		80		70		65		45	nS	
20	TdCr(M1r)	Clock Rise to /M1 Rise delay		100		80		70		65		45	nS	
21	TdCr(RFSHf)	Clock Rise to /RFSH Fall delay		130		110		95		80		60	nS	
22	TdCr(RFSHr)	Clock Rise to /RFSH Rise delay		120		100		85		80		60	nS	
23	TdCf(RDr)	Clock Fall to /RD Rise delay		85		70		60		55		40	nS	
24	TdCr(RDf)	Clock Rise to /RD Fall delay		85		70		60		55		40	nS	
25	TsD(Cf)	Data setup to Clock Fall during M2, M3, M4 or M5 cycles	50		40		30		25		12		nS	
26	TdA(IORQf)	Address stable prior to /IORQ Fall	180*		107*		75*		50*		0*		nS	
27	TdCr(IORQf)	Clock Rise to /IORQ Fall delay		75		65		55		50		40	nS	
28	TdCf(IORQr)	Clock Fall to /IORQ Rise delay		85		70		60		55		40	nS	
29	TdD(WRf)Mw	Data stable prior to /WR Fall	80*		22*		5*		40*		-10*		nS	
30	TdCf(WRf)	Clock Fall to /WR Fall delay		80		70		60		55		40	nS	
31	TwWR	/WR pulse width	220*		132*		100*		75*		25*		nS	
32	TdCf(WRr)	Clock Fall to /WR Rise delay		80		70		60		55		40	nS	
33	TdD(WRf)IO	Data stable prior to /WR Fall	-10*		-55*		-55*		-10*		-30*		nS	
34	TdCr(WRf)	Clock Rise to /WR Fall delay		65		60		60		50		40	nS	
35	TdWRr(D)	Data stable from /WR Rise	60*		30*		15*		10*		0*		nS	
36	TdCf(HALT)	Clock Fall to /HALT 'L' or 'H'		300		260		225		90		70	nS	
37	TwNMI	/NMI pulse width	80		60		60		60		60		nS	
38	TsBUSREQ (Cr)	/BUSREQ setup time to Clock Rise	50		50		40		30		15		nS	

*For clock periods other than the minimums shown, calculate parameters using the table on the following page. Calculated values above assumed TrC = TfC = 20 ns.

†Units in nanoseconds (ns).

†† **For loading ≥ 50 pf. Decrease width by 10 ns for each additional 50 pf.**

**4 MHz CMOS Z80 is obsoleted and replaced by 6 MHz

AC CHARACTERISTICS† (Z84C00/CMOS Z80 CPU; Continued)

V_{CC}=5.0V ± 10%, unless otherwise specified

No	Symbol	Parameter	Z84C0004** Min	Z84C0004** Max	Z84C0006 Min	Z84C0006 Max	Z84C0008 Min	Z84C0008 Max	Z84C0010 Min	Z84C0010 Max	Z84C0020[1] Min	Z84C0020[1] Max	Unit	Note
39	ThBUSREQ (Cr)	/BUSREQ hold time after Clock Rise	10		10		10		10		10		nS	
40	TdCr (BUSACKf)	Clock Rise to /BASACK Fall delay		100		90		80		75		40	nS	
41	TdCf (BUSACKr)	Clock Fall to /BASACK Rise delay		100		90		80		75		40	nS	
42	TdCr(Dz)	Clock Rise to Data float delay		90		80		70		65		40	nS	
43	TdCr(CTz)	Clock Rise to Control Outputs Float Delay (/MREQ, /IORQ, /RD and /WR)		80		70		60		65		40	nS	
44	TdCr(Az)	Clock Rise to Address float delay		90		80		70		75		40	nS	
45	TdCTr(A)	Address Hold time from /MREQ, /IORQ, /RD or /WR	80*		35*		20*		20*		0*		nS	
46	TsRESET(Cr)	/RESET to Clock Rise setup time	60		60		45		40		15		nS	
47	ThRESET(Cr)	/RESET to Clock Rise Hold time	10		10		10		10		10		nS	
48	TsINTf(Cr)	/INT Fall to Clock Rise Setup Time	80		70		55		50		15		nS	
49	ThINTr(Cr)	/INT Rise to Clock Rise Hold Time	10		10		10		10		10		nS	
50	TdM1f (IORQf)	/M1 Fall to /IORQ Fall delay	565*		359*		270*		220*		100*		nS	
51	TdCf(IORQf)	/Clock Fall to /IORQ Fall delay		85		70		60		55		45	nS	
52	TdCf(IORQr)	Clock Rise to /IORQ Rise delay		85		70		60		55		45	nS	
53	TdCf(D)	Clock Fall to Data Valid delay		150		130		115		110		75	nS	

Notes:

* For Clock periods other than the minimum shown, calculate parameters using the following table. Calculated values above assumed TrC = TfC = maximum.

** 4 MHz CMOS Z80 is obsoleted and replaced by 6 MHz

[1] Z84C0020 parameters are guuaranteed with 50pF load Capacitance.

[2] If Capacitive Load is other than 50pF, please use Figure 1. to calculate the value.

[3] Increasing delay by 10nS for each 50pF increase in loading, 200pF max for data lines, and 100pF for control lines.

FOOTNOTES TO AC CHARACTERISTICS

No	Symbol	Parameter	Z84C0004**	Z84C0006	Z84C0008	Z84C0010	Z84C0020
1	TcC	TwCh + TwCl + TrC + TfC					
7	TdA(MREQf)	TwCh + TfC	-65	-50	-45	-45	-45
10	TwMREQh	TwCh + TfC	-20	-20	-20	-20	-20
11	TwMREQl	TcC	-30	-30	-25	-25	-25
26	TdA(IORQf)	TcC	-70	-55	-50	-50	-50
29	TdD(WRf)	TcC	-170	-140	-120	-60	-60
31	TwWR	TcC	-30	-30	-25	-25	-25
33	TdD(WRf)	TwCl + TrC	-140	-140	-120	-60	-60
35	TdWRr(D)	TwCl + TrC	-70	-55	-50	-40	-25
45	TdCTr(A)	TwCl + TrC	-50	-50	-45	-30	-30
50	TdM1f(IORQf)	2TcC + TwCh + TfC	-65	-50	-45	-30	-30

AC Test Conditions: V_{IH} = 2.0 V, V_{IL} = 0.8 V; V_{OH} = 1.5 V, V_{OL} = 1.5 V; V_{IHC} = V_{CC} −0.6 V, V_{ILC} = 0.45 V; FLOAT = ±0.5 V

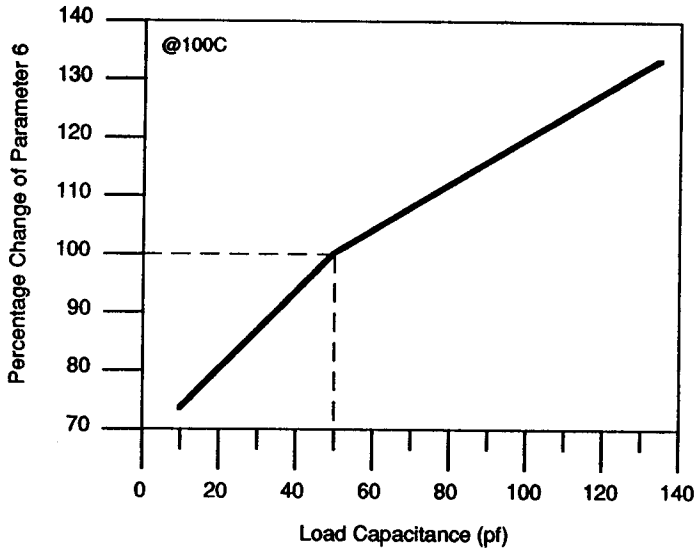


Figure 1. Address Delay Characteristics
(Parameter 6)

DC CHARACTERISTICS (Z8400/NMOS Z80 CPU)

All parameters are tested unless otherwise noted.

Symbol	Parameter	Min	Max	Unit	Test Condition
V_{ILC}	Clock Input Low Voltage	−0.3	0.45	V	
V_{IHC}	Clock Input High Voltage	V_{CC} −.6	V_{CC} +.3	V	
V_{IL}	Input Low Voltage	−0.3	0.8	V	
V_{IH}	Input High Voltage	2.0[1]	V_{CC}	V	
V_{OL}	Output Low Voltage		0.4	V	I_{OL} = 2.0 mA
V_{OH}	Output High Voltage	2.4[1]		V	I_{OH} = −250 μA
I_{CC}	Power Supply Current		200	mA	Note 3
I_{LI}	Input Leakage Current		10	μA	V_{IN} = 0 to V_{CC}
I_{LO}	3-State Output Leakage Current in Float	−10	10[2]	μA	V_{OUT} = 0.4 to V_{CC}

1. For military grade parts, refer to the Z80 Military Electrical Specification.
2. A_{15}-A_0, D_7-D_0, $\overline{MREQ}$, $\overline{IORQ}$, $\overline{RD}$, and $\overline{WR}$.
3. Measurements made with outputs floating.

CAPACITANCE

Guaranteed by design and characterization.

Symbol	Parameter	Min	Max	Unit
C_{CLOCK}	Clock Capacitance		35	pf
C_{IN}	Input Capacitance		5	pf
C_{OUT}	Output Capacitance		15	pf

NOTES:
T_A = 25°C, f = 1 MHz.
Unmeasured pins returned to ground.

AC CHARACTERISTICS† (Z8400/NMOS Z80 CPU)

Number	Symbol	Parameter	Z0840004 Min	Z0840004 Max	Z0840006 Min	Z0840006 Max	Z0840008 Min	Z0840008 Max
1	TcC	Clock Cycle Time	250*		162*		125*	
2	TwCh	Clock Pulse Width (High)	110	2000	65	2000	55	2000
3	TwCl	Clock Pulse Width (Low)	110	2000	65	2000	55	2000
4	TfC	Clock Fall Time		30		20		10
5	TrC	Clock Rise Time		30		20		10
6	TdCr(A)	Clock ↑ to Address Valid Delay		110		90		80
7	TdA(MREQf)	Address Valid to $\overline{MREQ}$ ↓ Delay	65*		35*		20*	
8	TdCf(MREQf)	Clock ↓ to $\overline{MREQ}$ ↓ Delay		85		70		60
9	TdCr(MREQr)	Clock ↑ to $\overline{MREQ}$ ↑ Delay		85		70		60
10	TwMREQh	$\overline{MREQ}$ Pulse Width (High)	110*‡‡		65*‡‡		45*‡‡	
11	TwMREQl	$\overline{MREQ}$ Pulse Width (Low)	220*‡‡		135*‡‡		100*‡‡	
12	TdCf(MREQr)	Clock ↓ to $\overline{MREQ}$ ↑ Delay		85		70		60
13	TdCf(RDf)	Clock ↓ to $\overline{RD}$ ↓ Delay		95		80		70
14	TdCr(RDr)	Clock ↑ to $\overline{RD}$ ↑ Delay		85		70		60
15	TsD(Cr)	Data Setup Time to Clock ↑	35		30		30	
16	ThD(RDr)	Data Hold Time to $\overline{RD}$ ↑		0		0		0
17	TsWAIT(Cf)	$\overline{WAIT}$ Setup Time to Clock ↓	70		60		50	
18	ThWAIT(Cf)	$\overline{WAIT}$ Hold Time after Clock ↓		0		0		0
19	TdCr(M1f)	Clock ↑ to $\overline{M1}$ ↓ Delay		100		80		70
20	TdCr(M1r)	Clock ↑ to $\overline{M1}$ ↑ Delay		100		80		70
21	TdCr(RFSHf)	Clock ↑ to $\overline{RFSH}$ ↓ Delay		130		110		95
22	TdCr(RFSHr)	Clock ↑ to $\overline{RFSH}$ ↑ Delay		120		100		85
23	TdCf(RDr)	Clock ↓ to $\overline{RD}$ ↑ Delay		85		70		60
24	TdCr(RDf)	Clock ↑ to $\overline{RD}$ ↓ Delay		85		70		60
25	TsD(Cf)	Data Setup to Clock ↓ during M_2, M_3, M_4, or M_5 Cycles	50		40		30	
26	TdA(IORQf)	Address Stable prior to $\overline{IORQ}$ ↓	180*		110*		75*	
27	TdCr(IORQf)	Clock ↑ to $\overline{IORQ}$ ↓ Delay		75		65		55
28	TdCf(IORQr)	Clock ↓ to $\overline{IORQ}$ ↑ Delay		85		70		60
29	TdD(WRf)	Data Stable prior to $\overline{WR}$ ↓	80*		25*		5*	
30	TdCf(WRf)	Clock ↓ to $\overline{WR}$ ↓ Delay		80		70		60
31	TwWR	$\overline{WR}$ Pulse Width	220*		135*		100*	
32	TdCf(WRr)	Clock ↓ to $\overline{WR}$ ↑ Delay		80		70		60
33	TdD(WRf)	Data Stable prior to $\overline{WR}$ ↓	−10*		−55*		55*	
34	TdCr(WRf)	Clock ↑ to $\overline{WR}$ ↓ Delay		65		60		55
35	TdWRr(D)	Data Stable from $\overline{WR}$ ↑	60*		30*		15*	
36	TdCf(HALT)	Clock ↓ to $\overline{HALT}$ ↑ or ↓		300		260		225
37	TwNMI	$\overline{NMI}$ Pulse Width	80		70		60*	
38	TsBUSREQ(Cr)	$\overline{BUSREQ}$ Setup Time to Clock ↑	50		50		40	

*For clock periods other than the minimums shown, calculate parameters using the table on the following page. Calculated values above assumed TrC = TfC = 20 ns.

†Units in nanoseconds (ns).

‡‡ For loading ≥ 50 pf., Decrease width by 10 ns for each additional 50 pf.

Customer Support

For answers to technical questions about the product, documentation, or any other issues with Zilog's offerings, please visit Zilog's Knowledge Base at http://www.zilog.com/kb.

For any comments, detail technical questions, or reporting problems, please visit Zilog's Technical Support at http://support.zilog.com.